Fujitsu Semiconductor Europe

Factsheet Fujitsu ARM Cortex Design Support



Fujitsu ARM Cortex Design Support



FASP Support (Fujitsu ARM® based SoC Prototyping Kit)

- FASP is a reference design concept of ARM based SoC
- All Fujitsu IPs are integrated into a reference design
- FASP consists of a reference design (RTL), simulation environment, example program (boot code), synthesis environment, net list, verification environment (FV script and example STA scripts)
- FASP enables the customer to shorten the design TAT and verification TAT
- FASP will support the following ARM cores:
 - CortexTM-M3
 - Cortex-A9
 - Cortex-R4F
 - Cortex-A5 (planned)
 - Cortex-A15 (planned)

ATR **Core Bock** PTM PTM PTM Cortex-A9 CPU Cortex-A9 CPU Cortex-A9 CPU ROM Table I-Cache D-Cache Snoop Control Unit APB MUX APB_DEC PL310 APB_SYNC Debug APB

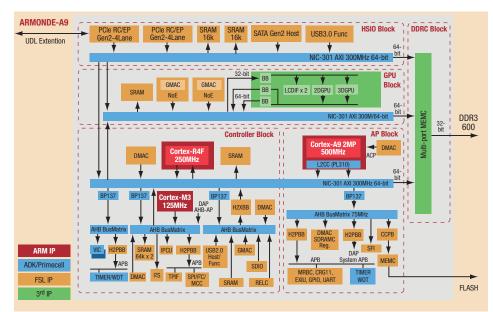
Cortex-A9 Block diagram

ARMONDE-A9 (ARM Evaluation Chip)

This ARM evaluation chip is targeted to develop high performance ARM based SoCs and contains therefore the Cortex-A9, Cortex-R4 and Cortex-M3 cores. In the future, the EV chip will have implemented Fujitsu advanced IPs like PClgen2, SATAgen2, USB3.0, etc. This EV chip enables designers to develop IP drivers and OS. Also, the TAT for SoC prototyping will be much shorter. An Evaluation Board will also be provided with the ARMONDE-A9. This board is available with an LCD monitor (touch panel) and FPGA for

user logic extension. The following deliverables are available with the board:

- FPGA reference design
- Software (OS: Linux, ITRON or Android)
- Drivers for IPs
- ARMONDE-A9 Block Diagram
- IPs used on ARMONDE-A9 (see table on P2)



Operating frequency (except as otherwise stated) AXI= 64-bit/300MHz, AHB= 32-bit/150MHz, APB= 32-bit/75MHz

ARMONDE-A9 Block diagram



| IPs on ARMONDE-A9 | 1 12 11 | |
|-------------------|------------------|--|
| Category | IP Name | Descriptions |
| Processor | Cortex-A9 MPcore | Dual-core, 500MHz, L1 cache I/D=32KB/32KB, L2 cache = 512KB, ACP-DMA |
| | Cortex-R4F | 250MHz, L1 cache =16KB/16KB, TCM_A=64KB, TCM_B0=32KB, TCM_B1=32KB |
| | Cortex-M3 | 125MHz |
| | GPU | OpenGL ES1.1/OpenGL ES2.0/OpenVG1.1, LCD Controller (2-ch) |
| Interface Macro | PCle | PCI Express Gen2, Root/Endpoint, 4-lanes (2-ch/SoC IF + FPGA extension) |
| | SATA | Serial ATA Host Gen2 |
| | USB3.0 | USB3.0 Function |
| | USB2.0 HDC | USB2.0 Host/Function DMAC |
| | GMAC | Ethernet MAC 1000/100base, 802.3az (LPI), GMII, IEEE1588 |
| | SDIO | UHS-1(eMMC) |
| | UART | UART (2-ch) |
| | I ² C | I ² C (1-ch) |
| | I ² S | I ² S (1-ch) + DMAC |
| | SSP (PL022) | Compatible with Motorola SPI, TI SSI and National Semiconductor Microwire |
| | NoE | 2ch IPSec Network Off-load Engine with GMAC4MT (700Mbps half duplex IPSEC) |
| | TPIF | Touch Panel Interface (Multi-touch detection) |
| Memory I/F | SDRAMC | DDR2/3-600MHz 32-bit |
| | MEMCS | Flash/SRAM Controller |
| | SPI | Quad Serial Flash Controller |
| CPU Peripherals | _ | VIC (Vectored Interrupt Controller), CRG11 (ClockReset Generator), IPCU (Inter-processor |
| | | Communication Unit), GPIO, Watchdog, Timer, MRBC (Remap and Boot Controller), SYSOC |
| | | (System Operation Controller), SRAM on AXI (128KB), SRAM on AHB (64KB x2) |
| Bus Interconnect | NIC-301 | ARM Network Interconnect (AXI, AHB, APB) |
| | AHB BusMatrix | AHB Interconnect |
| Others | OPAL/RELC/ADC | Instruction encryption/data compression and decompression / ADC 2ch for touch panel cor |

High-speed Cortex-A9 HLB (Hierarchical Layout Block)

65nm: 600MHz40nm: 800MHz28nm: 1000MHz